

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6758717

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SHANGSHU KIM	03/12/2021
YOUNGHO LEE	03/12/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	METAL LINK INC.
<b>Street Address:</b>	550, DEOKHO-RO, SAMSEONG-MYEON
<b>City:</b>	EUMSEONG-GUN CHUNGCHONGBUK-DO
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	27647
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17281559
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(603)668-2970
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<b>ATTORNEY DOCKET NUMBER:</b>	EZP088
<b>NAME OF SUBMITTER:</b>	KEVIN J. CARROLL
<b>SIGNATURE:</b>	/KEVIN J. CARROLL/
<b>DATE SIGNED:</b>	06/11/2021
<b>Total Attachments: 3</b>	
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source=EZP088-ExecAssignment-ASFILED-FINAL#page3.tif	

## ASSIGNMENT OF THE UNITED STATES PATENT APPLICATION

WHEREAS, I/WE, Shangshu KIM and Youngho LEE made certain new and useful inventions and improvements for which I/We filed, or will be filing, an application for Letters Patent of the United States, identified as U.S. patent application serial number 17/281,559 filed on March 30, 2021, which application is entitled:

### OPTICAL FIBER COMPOSITE GROUND WIRE USING COMPOSITE MATERIAL

AND, WHEREAS, I/We hereby authorize and request an attorney associated with Customer Number 32047 to insert on the designated lines above, the filing date and application number of said application when known;

AND, WHEREAS, METAL LINK INC., a corporation organized and existing under and by virtue of the laws of Republic of Korea, and having an office and place of business at 550, Deokho-ro, Samseong-myeon, Eumseong-gun Chungcheongbuk-do, 27647, REPUBLIC OF KOREA, (hereinafter "Assignee"), is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefore;

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, I/We have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted there from, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed under the Patent Cooperation Treaty, in any regional patent offices and in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted there from; and I/We do hereby authorize and request the Commissioner of Patents and Trademarks to

issue any and all United States Letter Patent for the aforesaid inventions and improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the said Assignee, its successors and assigns.

AND, for the consideration aforesaid, I/We do hereby agree that I/We and my/our executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors and representatives all facts known to me/us relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors or assigns the entire right, title and interest in and to the said improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be;

AND, furthermore, I/We covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by me and that full right to convey the same as herein expressed is possessed by me/us.

AND, as a named inventor, I hereby declare that:

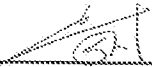
The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

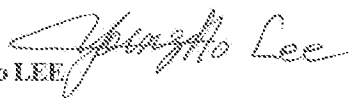
I have reviewed and understand the contents of the application, including the claims, and I am aware of the duty to disclose to the Office all information known to the person to be material to patentability as defined in 37 C.F.R. § 1.56.

I hereby acknowledge that any wilful false statement made in this declaration is punishable under 18 U.S. C. 1001 by fine or imprisonment of not more than five (5) years, or both.

IN TESTIMONY WHEREOF, I have hereunto set my hand this 14 day of 3, 2021.

  
\_\_\_\_\_  
Shangshu KIM

IN TESTIMONY WHEREOF, I have hereunto set my hand this 12 day of 03, 2021.

  
Youngho LEE